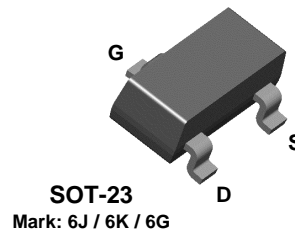
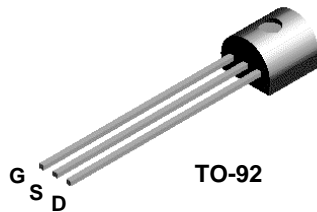


**PN4391  
PN4392  
PN4393**

**MMBF4391  
MMBF4392  
MMBF4393**



NOTE: Source & Drain  
are interchangeable

## N-Channel Switch

This device is designed for low level analog switching, sample and hold circuits and chopper stabilized amplifiers. Sourced from Process 51. See J111 for characteristics.

### Absolute Maximum Ratings\* TA = 25°C unless otherwise noted

| Symbol         | Parameter  | Value       | Units |
|----------------|--|-------------|-------|
| $V_{DG}$       | Drain-Gate Voltage                               | 30          | V     |
| $V_{GS}$       | Gate-Source Voltage                              | - 30        | V     |
| $I_{GF}$       | Forward Gate Current                             | 50          | mA    |
| $T_J, T_{stg}$ | Operating and Storage Junction Temperature Range | -55 to +150 | °C    |

\*These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

**NOTES:**

- 1) These ratings are based on a maximum junction temperature of 150 degrees C.
- 2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations

### Thermal Characteristics TA = 25°C unless otherwise noted

| Symbol          | Characteristic                                | Max         |                | Units |
|-----------------|---|-------------|----------------|-------|
|                 |   | PN4391-4393 | *MMBF4391-4393 |       |
| $P_D$           | Total Device Dissipation<br>Derate above 25°C | 625         | 350            | mW    |
|                 |   | 5.0         | 2.8            | mW/°C |
| $R_{\theta JC}$ | Thermal Resistance, Junction to Case          | 125         |                | °C/W  |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient       | 357         | 556            | °C/W  |

\*Device mounted on FR-4 PCB 1.6" X 1.6" X 0.06."

# N-Channel Switch

(continued)

## Electrical Characteristics

TA = 25°C unless otherwise noted

| Symbol                              | Parameter                        | Test Conditions   | Min  | Max                                    | Units                            |                |
|-------------------------------------|----------------------------------|---|--|--|----------------------------------|----------------|
| <b>OFF CHARACTERISTICS</b>          |                                  |   |  |  |                                  |                |
| V <sub>(BR)GSS</sub>                | Gate-Source Breakdown Voltage    | I <sub>G</sub> = 1.0 μA, V <sub>DS</sub> = 0  | - 30   |  | V                                |                |
| I <sub>GSS</sub>                    | Gate Reverse Current             | V <sub>GS</sub> = - 15 V, V <sub>DS</sub> = 0<br>V <sub>GS</sub> = - 15 V, V <sub>DS</sub> = 0, T <sub>A</sub> = 150°C  |  | - 1.0<br>- 0.2                         | nA<br>μA                         |                |
| V <sub>GS(off)</sub>                | Gate-Source Cutoff Voltage       | V <sub>DS</sub> = 20 V, I <sub>D</sub> = 1.0 nA   | 4391<br>4392<br>4393                         | - 4.0<br>- 2.0<br>- 3.0                | V<br>V<br>V                      |                |
| V <sub>GS(f)</sub>                  | Gate-Source Forward Voltage      | I <sub>G</sub> = 1.0 mA, V <sub>DS</sub> = 0  |  | 1.0                                    | V                                |                |
| I <sub>D(off)</sub>                 | Drain Cutoff Leakage Current     | V <sub>DS</sub> = 20 V, V <sub>GS</sub> = - 12 V<br>V <sub>DS</sub> = 20 V, V <sub>GS</sub> = - 7.0 V<br>V <sub>DS</sub> = 20 V, V <sub>GS</sub> = - 5.0 V<br>V <sub>DS</sub> = 20 V, V <sub>GS</sub> = - 12 V,<br>T <sub>A</sub> = 150°C<br>V <sub>DS</sub> = 20 V, V <sub>GS</sub> = - 7.0 V,<br>T <sub>A</sub> = 150°C<br>V <sub>DS</sub> = 20 V, V <sub>GS</sub> = - 5.0 V,<br>T <sub>A</sub> = 150°C | 4391<br>4392<br>4393<br>4391<br>4392<br>4393 | 0.1<br>0.1<br>0.1<br>0.2<br>0.2<br>0.2 | nA<br>nA<br>nA<br>μA<br>μA<br>μA |                |
| <b>ON CHARACTERISTICS</b>           |                                  |   |  |  |                                  |                |
| I <sub>DSS</sub>                    | Zero-Gate Voltage Drain Current* | V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0   | 4391<br>4392<br>4393                         | 50<br>25<br>5.0                        | 150<br>75<br>30                  | mA<br>mA<br>mA |
| V <sub>DS(on)</sub>                 | Drain-Source On Voltage          | I <sub>D</sub> = 12 mA, V <sub>GS</sub> = 0<br>I <sub>D</sub> = 6.0 mA, V <sub>GS</sub> = 0<br>I <sub>D</sub> = 3.0 mA, V <sub>GS</sub> = 0   | 4391<br>4392<br>4393                         |  | 0.4<br>0.4<br>0.4                | V<br>V<br>V    |
| r <sub>DS(on)</sub>                 | Drain-Source On Resistance       | I <sub>D</sub> = 1.0 mA, V <sub>GS</sub> = 0  | 4391<br>4392<br>4393                         |  | 30<br>60<br>100                  | Ω<br>Ω<br>Ω    |
| <b>SMALL-SIGNAL CHARACTERISTICS</b> |                                  |   |  |  |                                  |                |
| r <sub>DS(on)</sub>                 | Drain-Source On Resistance       | V <sub>DS</sub> = V <sub>GS</sub> = 0, f = 1.0 kHz  | 4391<br>4392<br>4393                         |  | 30<br>60<br>100                  | Ω<br>Ω<br>Ω    |
| C <sub>iss</sub>                    | Input Capacitance                | V <sub>DS</sub> = 20, V <sub>GS</sub> = 0, f = 1.0 MHz  |  |  | 14                               | pF             |
| C <sub>rss</sub>                    | Reverse Transfer Capacitance     | V <sub>GS</sub> = - 12 V, f = 1.0 MHz<br>V <sub>GS</sub> = - 7.0 V, f = 1.0 MHz<br>V <sub>GS</sub> = - 5.0 V, f = 1.0 MHz   | 4391<br>4392<br>4393                         |  | 3.5<br>3.5<br>3.5                | pF<br>pF<br>pF |
| <b>SWITCHING CHARACTERISTICS</b>    |                                  |   |  |  |                                  |                |
| t <sub>r</sub>                      | Rise Time                        | I <sub>D(on)</sub> = 12 mA<br>I <sub>D(on)</sub> = 6.0 mA<br>I <sub>D(on)</sub> = 3.0 mA  | 4391<br>4392<br>4393                         |  | 5.0<br>5.0<br>5.0                | ns<br>ns<br>ns |
| t <sub>f</sub>                      | Fall Time                        | V <sub>GS(off)</sub> = 12 V<br>V <sub>GS(off)</sub> = 6.0 V<br>V <sub>GS(off)</sub> = 3.0 V   | 4391<br>4392<br>4393                         |  | 15<br>20<br>30                   | ns<br>ns<br>ns |
| t <sub>on</sub>                     | Turn-On Time                     | I <sub>D(on)</sub> = 12 mA<br>I <sub>D(on)</sub> = 6.0 mA<br>I <sub>D(on)</sub> = 3.0 mA  | 4391<br>4392<br>4393                         |  | 15<br>15<br>15                   | ns<br>ns<br>ns |
| t <sub>off</sub>                    | Turn-Off Time                    | V <sub>GS(off)</sub> = 12 V<br>V <sub>GS(off)</sub> = 6.0 V<br>V <sub>GS(off)</sub> = 3.0 V   | 4391<br>4392<br>4393                         |  | 20<br>35<br>50                   | ns<br>ns<br>ns |

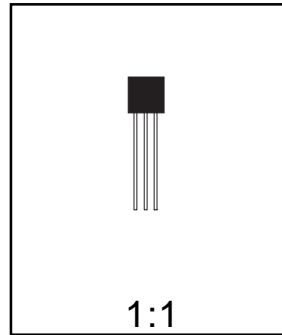
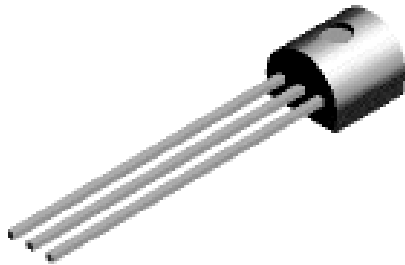
\*Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 1.0%

PN4391 / 4392 / 4393 / MMBF4391 / 4392 / 4393

# TO-92 Package Dimensions



## TO-92 (FS PKG Code 92, 94, 96)



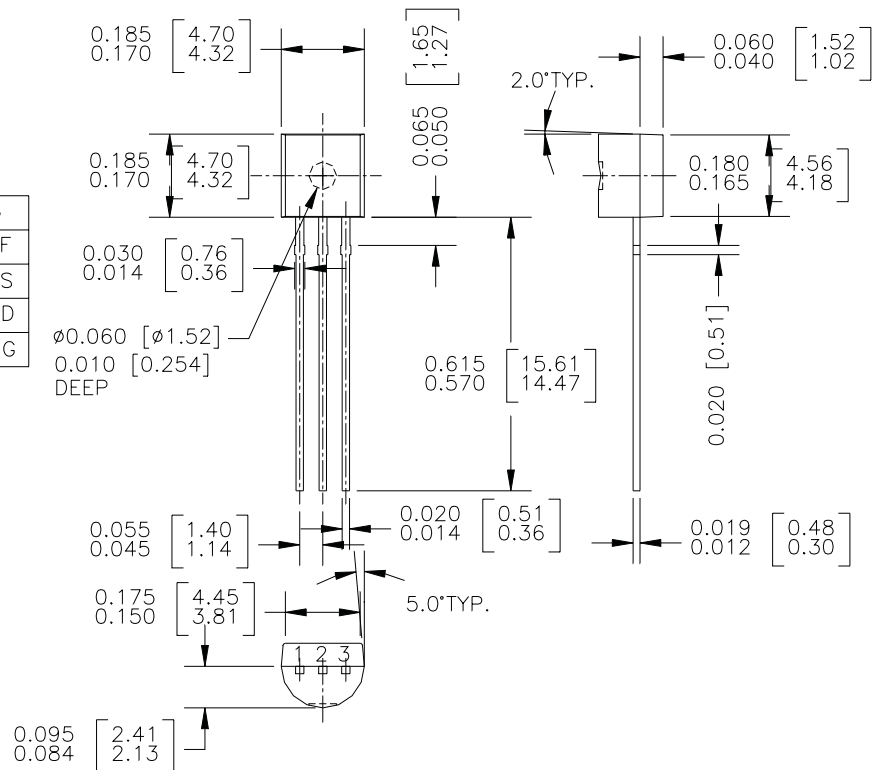
Scale 1:1 on letter size paper

Dimensions shown below are in:  
inches [millimeters]

Part Weight per unit (gram): 0.1977

TO-92 (92,94,96)

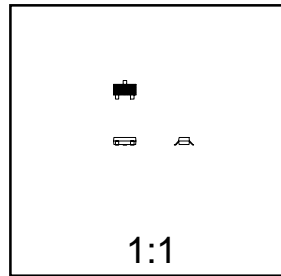
| PIN | 92 |   | 94 |   | 96 |   |
|-----|----|---|----|---|----|---|
|     | B  | F | B  | F | B  | F |
| 1   | E  | D | E  | D | B  | S |
| 2   | B  | S | C  | G | E  | D |
| 3   | C  | G | B  | S | C  | G |



# SOT-23 Package Dimensions



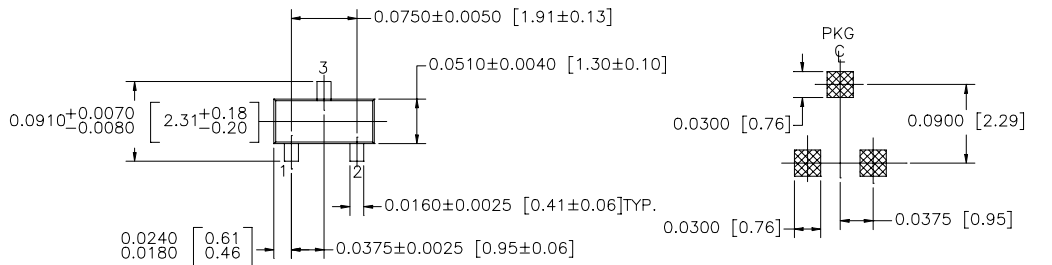
## SOT-23 (FS PKG Code 49)



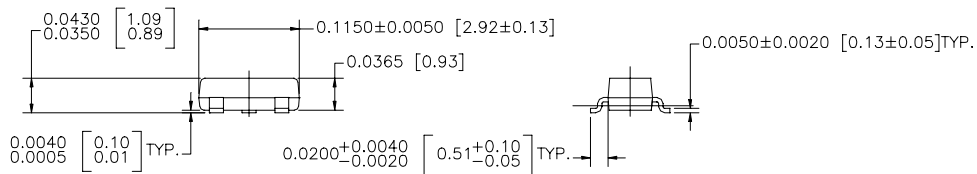
Scale 1:1 on letter size paper

Dimensions shown below are in:  
inches [millimeters]

Part Weight per unit (gram): 0.0082



LAND PATTERN RECOMMENDATION



CONTROLLING DIMENSION IS INCH  
VALUES IN [ ] ARE MILLIMETERS

SOT 23, 3 LEADS LOW PROFILE

NOTE : UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH 150 MICRONS / 3.81 MICROMETERS  
MINIMUM TIN / LEAD (SOLDER) ON ALLOY 42
- REFERENCE JEDEC REGISTRATION TO-236, VARIATION AB, ISSUE G, DATED JUL 1993

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| CoolFET™             | GTO™                | QS™                 | UHC™       |
| CROSSVOLT™           | HiSeC™              | QT Optoelectronics™ | VCX™       |
| DOME™                | ISOPLANAR™          | Quiet Series™       |            |
| E <sup>2</sup> CMOS™ | MICROWIRE™          | SILENT SWITCHER®    |            |
| EnSigna™             | OPTOLOGIC™          | SMART START™        |            |
| FACT™                | OPTOPLANAR™         | SuperSOT™-3         |            |
| FACT Quiet Series™   | PACMAN™             | SuperSOT™-6         |            |
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